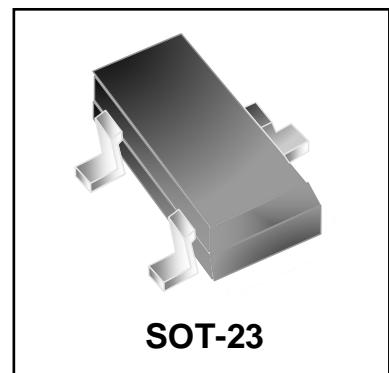
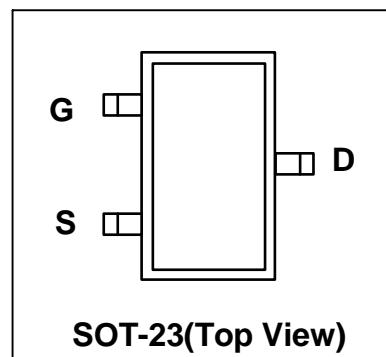
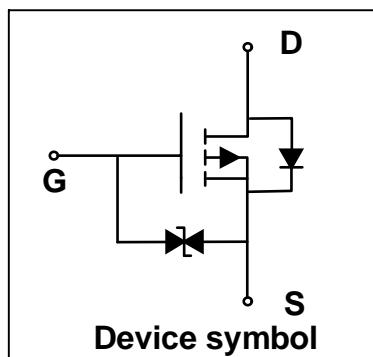


Features

- Way-on Small Signal MOSFETs
- $V_{DS} = -20V$, $I_D = -4A$
 $R_{DS(on)} < 39m\Omega$ @ $V_{GS} = -4.5V$
 $R_{DS(on)} < 50m\Omega$ @ $V_{GS} = -2.5V$
- Trench LV MOSFET Technology
- ESD Protected

**Mechanical Characteristics**

- SOT-23 Package
- Marking : Making Code
- RoHS Compliant

Schematic & PIN Configuration**Absolute Maximum Rating ($T_A=25^\circ C$ unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current $T_A = 25^\circ C$	I_D	-4	A
Pulsed Drain Current ¹	I_{DM}	-16	A
Power Dissipation $T_A = 25^\circ C$	P_D	1.08	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	115	$^\circ C/W$

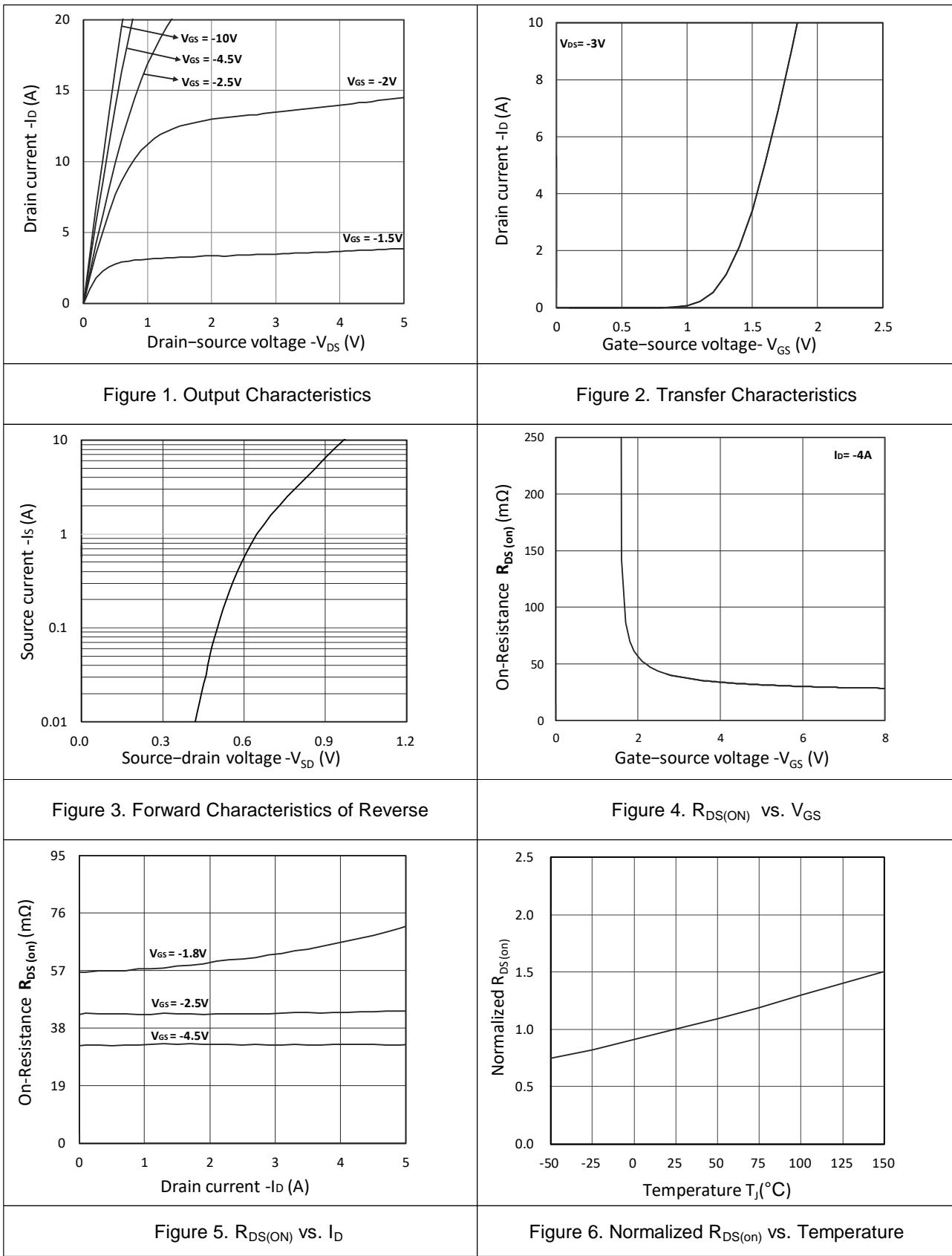
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-20	-	-	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 10V$	-	-	± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$	-	-	-1	μA
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.35	-0.65	-0.9	V
Drain-Source on-Resistance ³	$R_{DS(\text{on})}$	$V_{GS} = -4.5V, I_D = -4A$	-	32	39	$\text{m}\Omega$
		$V_{GS} = -2.5V, I_D = -3A$	-	42	50	
		$V_{GS} = -1.8V, I_D = -2A$	-	62	82	
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -10V, f = 1\text{MHz}$	-	1022	-	pF
Output Capacitance	C_{oss}		-	123	-	
Reverse Transfer Capacitance	C_{rss}		-	105	-	
Switching Characteristics⁴						
Total Gate Charge	Q_g	$V_{GS} = -4.5V, V_{DS} = -10V, I_D = -4A$	-	9.5	-	nC
Gate-Source Charge	Q_{gs}		-	1.2	-	
Gate-Drain Charge	Q_{gd}		-	2.3	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = -4.5V, V_{DD} = -10V, R_G = 3\Omega, I_D = -4A$	-	11	-	ns
Rise Time	t_r		-	9.5	-	
Turn-off Delay Time	$t_{d(off)}$		-	18	-	
Fall Time	t_f		-	24	-	
Drain-Source Body Diode Characteristics						
Body Diode voltage ³	V_{DS}	$I_S = -1A, V_{GS} = 0V$	-	-	-1	V
Continuous Source Current	I_S	-	-	-	-4	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})} = 150^\circ\text{C}$.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



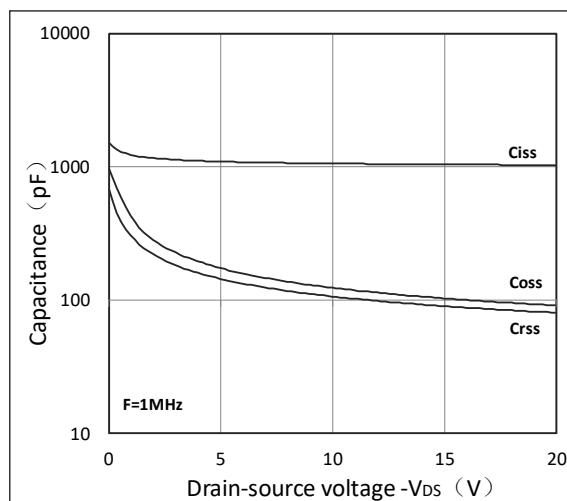


Figure 7. Capacitance Characteristics

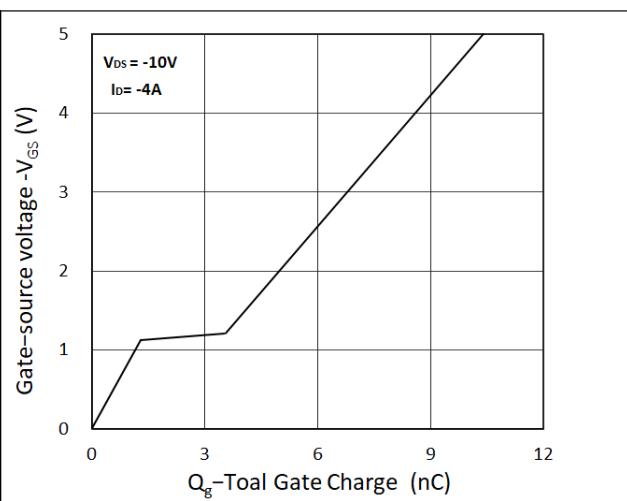
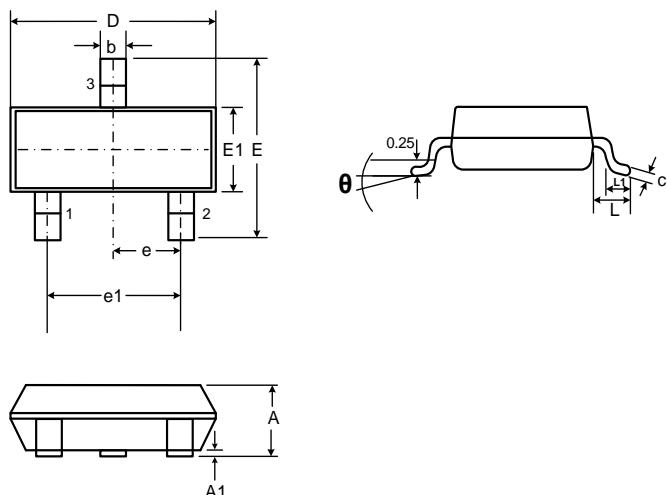
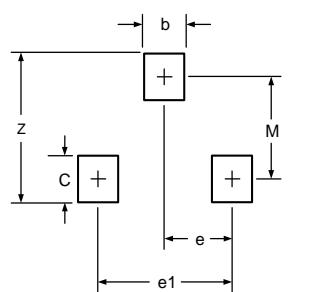


Figure 8. Gate Charge Characteristics

Outline Drawing – SOT-23

PACKAGE OUTLINE				
				
				
DIMENSIONS				
SYMBOL	MILLIMETER	MIN	MAX	INCHES
A	0.90	0.90	1.15	0.035
A1	0.00	0.00	0.10	0.000
b	0.30	0.30	0.50	0.012
c	0.08	0.08	0.15	0.003
D	2.80	2.80	3.00	0.110
E	2.25	2.25	2.55	0.089
E1	1.20	1.20	1.40	0.047
e	0.95 BSC	0.037BSC		
e1	1.80	1.80	2.00	0.071
L	0.55REF	0.022REF		
L1	0.30	0.30	0.50	0.012
θ	0°	0°	8°	0°
Notes				
1. Dimensioning and tolerances per ANSI Y14.5M, 1985.				
2. Controlling Dimension: Inches				
3. Pin 3 is the cathode (Unidirectional Only).				
4. Dimensions are exclusive of mold flash and metal burrs.				

Marking Codes

Part Number	WM02P40ME
Marking Code	

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.